

IN THE SPECIFICATION

Please replace the paragraph at page 13, line 7 with the following replacement paragraph:

Thus, as described above, the adapter frame of the present invention allows output die carriers, such as waffle packs or GEL-PAK carriers, to be presented to conventional die attach and die sort machines in the same or similar manner as that of normal tape mounted wafers. As a result, conventional die sorters can be used. Further, since the adapter frames are handled similarly to output wafers, waffle pack or Gel-Pak die carriers can be placed onto the adapter frames for processing without the need to install and/or replace specific handlers for these types of die carriers. This increases throughput and reduces costs of the semiconductor die manufacturing process. ~~This increases throughput and reduces costs of the semiconductor die manufacturing process.~~